

Tputty[™] 607

High Performance Dispensable Gap Filler



PRODUCT DESCRIPTION

Laird Tputty[™] 607 is a high thermally conductive single part dispensable material designed with automation and vertical stability in mind. Laird has leveraged its knowledge of thermally conductive fillers and resin systems to develop a single part dispensable that demonstrates reliability in a variety of application orientations.

Tputty[™] 607 is ideal for applications that can benefit from automation and allows minimization of SKUs in applications with gap variability. In addition to providing application flexibility and variable gap adaptation, Tputty[™] 607 will exert minimal stress on your component while maintaining interface contact to maximize thermal transfer. Combined with Laird's global technical support and global footprint, deploying Tputty[™] 607 is easier than ever.

FEATURES AND BENEFITS

- RoHS compliant
- Complete dispensing solution options available
- 6.4 W/mK
- Demonstrated thermal cycling stability
- Low outgassing per ASTM E595
 Available in cartridges (30cc, 75cc, 180cc, 360cc, 600cc)
 and pails (1 gallon and 5 gallon)

Packaging Size	Fill Volume	Fill Weight
30cc	30cc	105g
75cc (2.5 oz)	58cc	200g
180cc (6 oz)	161cc	556g
360cc (12 oz)	328cc	1130g
600cc (20 oz)	605cc	2090g
1 gallon	4090cc	14kg
5 gallon	5860cc	20kg

THR-DS-Tputty 607 03/17/2021

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TYPICAL PROPERTIES

PROPERTY	TYPICAL VALUE	METHOD
Construction	Ceramic filled silicone dispensable	
Color	Blue	Visual
Thermal Conductivity	6.4 W/mK	Hot Disk
Flow Rate (75cc taper tip, 0.125" orifice, 90 psi)	60 g/min	Laird Test Method - A16724-00
Density	3.45 g/cc	Helium Pycnometer
Flammability	V-0	UL 94
Operating Temperature Range	-40 to 200°C	Laird Test Method
Outgassing TML (weight)	0.204 %	ASTM E595
Outgassing CVCM (weight)	0.01 %	ASTM E595
Dielectric Breakdown	>6000 VAC (at 1 mm)	ASTM D149
Dielectric Constant @ 1MHz	15.0	ASTM D150
Minimum Bond line Thickness	0.150 mm (0.006")	Laird Test Method - A16112-00
Volume Resistivity	10 ¹³ ohm·cm	ASTM D257

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